Vin = 10V to 20V DC

At 10V input, RHPZ is at 8KHz
Crossover occurs at 10KHz

All power ground connections should be
connected together near the AGND pin and a single
sensitive low power ground connection should be
connected together near the AGND pin and a single
connection should be made to the single point GND.

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Heat Sink Required: Use TSS805K-06B for Layout. (Information in TASS811 Sheet)

Engineer: Ambreesh Tripathi

Contact: "34"

Assembly Variant: "35"

Sheet Title: "36"

Project Title: "37"

Designed for: "38"

1206 or 1210 footprint for these decoupling capacitors was chosen to have the possibility to take the audio output trace directly under the capacitor in layout.

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Update the Label Text in the Label Table as needed for each Assembly Variant.

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